

REMARKS

I. STATUS OF THE CLAIMS

Claims 4 and 14 are canceled herein.

Therefore, it is respectfully submitted that claims 1-3, 5-8, 10-13 and 15-19 are currently pending.

II. REJECTION OF CLAIM 1-8 AND 19 UNDER 35 USC 103 AS BEING UNPATENTABLE OVER AOKI IN VIEW OF UEMURA

In the present invention as recited, for example, in claim 1, a substrate assembly for a gas discharge panel comprises a dielectric layer and a protective layer of MgO formed in this order on a substrate having electrodes.

As recited, for example, in claim 1, the dielectric layer is a laminate of an organic dielectric layer and an inorganic dielectric layer in this order from a side of the substrate.

With the configuration as recited, for example, in claim 1, the inorganic dielectric layer is between the protective layer and the organic dielectric layer.

With the inorganic dielectric layer between the protective layer and the organic dielectric layer, it is possible to prevent peeling off of the organic dielectric layer at the formation of the MgO layer. See, for example, page 20, lines 17-21, of the specification.

Aoki discloses a silicone resin having an alkyl group and an aryl group that is used for a dielectric layer. See, for example, paragraphs [0041], [0055] and [0062], of Aoki.

However, Aoki does not disclose or suggest that two dielectric layers are used. Therefore, Aoki does not disclose or suggest the use of an organic dielectric layer and an inorganic dielectric layer as recited, for example, in claim 1.

Moreover, Aoki does not relate to solving the problem of preventing peeling off of an organic dielectric layer at the formation of a MgO layer in a multilayer structure.

Uemura discloses a dielectric layer 26 made of a low melting point glass, a second metal oxide layer 27-1 made of TiO₂ and a first metal oxide layer 27-2 made of MgO. See, for example, column 5, lines 27-38; column 9, lines 1-4; and Example 3, of Uemura. The first and second metal oxide layers of Uemura are a layer having a function as a protective layer.

However, Uemura does not describe that the second metal oxide layer can be used as a dielectric layer. Therefore, it is respectfully submitted that Uemura lacks motivation to use two dielectric layers.

Further, as indicated above, with the inorganic dielectric layer between the protective layer and the organic dielectric layer as recited, for example, in claim 1, it is possible to prevent

the organic dielectric layer from peeling off at the formation of the MgO layer. See, for example, page 20, lines 17-21, of the specification. In comparison, in Uemura, the second metal oxide layer is provided in order to match the linear thermal expansion coefficient of the protective layer to that of the dielectric layer, thereby preventing cracks in the protective layer. See, for example, column 3, lines 1-38; and column 6, lines 25-33, of Uemura.

Moreover, Uemura does not relate to solving the problem of preventing peeling off of an organic dielectric layer at the formation of a MgO layer in a multilayer structure.

Therefore, the reasons for providing the inorganic dielectric layer in embodiments of the present invention are completely different than the reasons for providing the second metal oxide layer in Uemura.

On page 4 of the Office Action, the Examiner asserts that the second metal oxide layer 27-1 made of TiO_2 in Uemura would inherently have dielectric properties due to the use of TiO_2 .

However, even assuming for the sake of argument that the second metal oxide layer of Uemura has inherent dielectric properties (although the Applicant's do not admit that the second metal oxide layer of Uemura acts as a dielectric), the second metal oxide layer of Uemura is provided for a significantly different reason than the inorganic dielectric layer as recited, for example, in claim 1. More specifically, as indicated above, with an inorganic dielectric layer as recited, for example, in claim 1, it is possible to prevent the organic dielectric layer from peeling off at the formation of the MgO layer. Uemura does not disclose or suggest such use of a dielectric layer. Instead, as indicated above, in Uemura, the second metal oxide layer is provided in order to match the linear thermal expansion coefficient of the protective layer to that of the dielectric layer, thereby preventing cracks in the protective layer.

Please note that claim 1 is amended herein to recite that the inorganic dielectric layer is made of a material selected from a group consisting of SiO_2 , Al_2O_3 , ZrO_2 , AlN , Si_3N_4 and SiC , and a mixture of two or more thereof. Similar amendments are made to claim 11. Support for the amendments is found, for example, in claims 4 and 14 which are canceled herein. **The cited references do not disclose the use of these materials.**

Accordingly, it is respectfully submitted that Aoki and Uemura should not be combined in the manner suggested by the Examiner and, even if combined, would not attain a structure as recited, for example, in the amended claim 1.

Although the above comments are specifically directed to claim 1, it is respectfully submitted that the comments would be helpful in understanding various differences of various other claims over the cited references.

On page 3 of the Office Action, the Examiner asserts that the limitation of "the organic

dielectric layer and the inorganic dielectric layer are formed together as a laminate" in claim 11 is not given patentable weight by the Examiner. Therefore, claim 11 is amended herein so that the limitation is considered by the Examiner.

In view of the above, it is respectfully submitted that the rejection is overcome.

III. CONCLUSION

In view of the above, it is respectfully submitted that the application is in condition for allowance, and a Notice of Allowance is earnestly solicited.

If any further fees are required in connection with the filing of this response, please charge such fees to our Deposit Account No. 19-3935.

Respectfully submitted,

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